

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 04116859 A

(43) Date of publication of application. 17.04.92

(51) Int. Cl.

H01L 25/065
H01L 21/60
H01L 25/07
H01L 25/18

(21) Application number: 02237713

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(22) Date of filing: 06.09.80

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(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To reduce the size of a package by forming a chip wherein the circuit function of a semiconductor device is divided into two chips, and sealing said chips which are stacked in the same package.

CONSTITUTION: The title semiconductor device is formed by dividing a chip constituting a circuit into two chips, and sealing the divided chips which are stacked. Thereby a chip size is restrained and the defective rate can be decreased. Since the package size is reduced, the mounting area can be made small.

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